Minutes from OpenPICs WP 3 meeting 17-07-2017

Part I (14:00-15:00): Weiming (chairing), Rui, Roel, Rob, Valentina, Kevin, Meint, Longfei, Michael

Discussion/action points

Nr.	Description	Responsible
1.	**Standard Pad layout** Exchange proposed pad layout template with Technobis and ask for their feedback.	Weiming
2.	**Mode mismatch issue Triplex-InP** Contact Lionix to work out solutions for the mode mismatch problem discussed between Smart MPW chips and Triplex chips.	Valentina
3.	**Agenda for Review Meeting** Circulate around proposal for review meeting agenda	Weiming
4.	**SP19 Chips** Discussion on measurement plan for SP19 structures, including plating resistance characterization at DC and RF, trench cross section SEM and contact resistance measurements.	
5.	**Measurement Template** Discussion on chip and measurement description file in YAML format with example of PixApp pad layout and BB test cell. Possibility to extend to data exchange file either in YAML or JSON format.	

Next meeting is 14th August, 2017, 14:00